

Approved by:

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SPECIFICATION

PRODUCT:SAW RESONATORMODEL:HR809TO-39

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HR809

The HR809 is a true one-port, surface-acoustic-wave (**SAW**) resonator in a low-profile metal **TO-39** case. It provides reliable, fundamental-mode, quartz frequency stabilization i.e. in transmitters or local oscillators operating at **809.000** MHz.

Pin

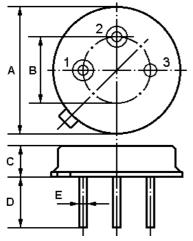
Pin1

0.50

From 50 Ω

source

1.Package Dimension (TO-39)



Input / Output 1 2 Output / Input 3 Case Ground Dimension Data (unit: mm) 9.30±0.20 A в 5.08±0.10 С 3.40±0.20 D 3±0.20 / 5±0.20 Е 0.45±0.20 3.Equivalent LC Model and Test Circuit

Configuration

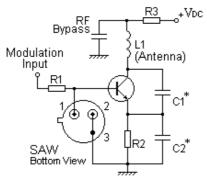
2.Marking

HR809

Color: Black or Blue

4.Typical Application Circuits

1) Low-Power Transmitter Application



5.Typical Frequency Response

D1:Transmission /M Log Mag 2.0 dB/ Ref 2.00 dB D2:Transmission

 V2: Transmission

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 Center 809.000 MHz

 Span 1.500 MHz

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Equivalent LC Model

RM LM CM

Co=Cp+ 0.25pF* * Case Parasitics

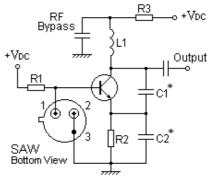
0.5pF

Pin 2

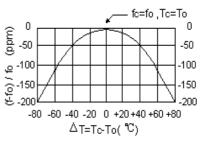
To 50 Ω

load

2) Local Oscillator Application



6.Temperature Characteristics



The curve shown above accounts for resonator contribution only and does not include oscillator temperature characteristics.

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7.Performance

7-1.Maximum Ratings

Rating		Value	Unit
CW RF Power Dissipation	Р	0	dBm
DC Voltage Between Any two Pins	V _{DC}	± 30	V
Storage Temperature Range	$T_{\rm stg}$	-40 to +85	
Operating Temperature Range	T _A	-10 to +60	

7-2. Electronic Characteristics

	Characteristic	Sym	Minimum	Typical	Maximum	Unit
Center Frequency (+25)	Absolute Frequency	f _C	808.750		809.150	MHz
	Tolerance from 809.000MHz	Δf_{C}		± 150		kHz
Insertion Loss		IL		1.2	1.6	dB
Quality Factor	Unloaded Q	Q _U		12,270		
	50 Ω Loaded Q	QL		1,600		
Temperature Stability	Turnover Temperature	T ₀	25	39	55	
	Turnover Frequency	f ₀		fc		kHz
	Frequency Temperature Coefficient	FTC		0.032		ppm/ ²
Frequency Aging	Absolute Value during the First Year	$ \mathbf{f}_{A} $		10		ppm/yr
DC Insulation Resistance Between Any Two Pins			1.0			MΩ
RF Equivalent RLC Model	Motional Resistance	R _M		15	20	Ω
	Motional Inductance	L _M		36.2168		μH
	Motional Capacitance	C _M		1.0697		fF
	Pin 1 to Pin 2 Static Capacitance	C ₀	2.6	2.9	3.2	pF

(i)CAUTION: Electrostatic Sensitive Device. Observe precautions for handling!

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- 1. The center frequency, f_C, is measured at the minimum IL point with the resonator in the 50 test system.
- 2. Unless noted otherwise, case temperature $T_C = +25^{\circ}C \pm 2^{\circ}C$.
- Frequency aging is the change in f_c with time and is specified at +65°C or less. Aging may exceed the specification for prolonged temperatures above +65°C. Typically, aging is greatest the first year after manufacture, decreasing in subsequent years.
- 4. Turnover temperature, T_0 , is the temperature of maximum (or turnover) frequency, f_0 . The nominal frequency at any case temperature, T_c , may be calculated from: $f = f_0 [1 FTC (T_0 T_c)^2]$.
- This equivalent RLC model approximates resonator performance near the resonant frequency and is provided for reference only. The capacitance C₀ is the measured static (nonmotional) capacitance between Pin1 and Pin2. The measurement includes case parasitic capacitance.

6. Derived mathematically from one or more of the following directly measured parameters: f_c , IL, 3 dB bandwidth, f_c www.DataSheversus T_c , and C_0 .

- 7. The specifications of this device are based on the test circuit shown above and subject to change or obsolescence without notice.
- 8. Typically, equipment utilizing this device requires emissions testing and government approval, which is the responsibility of the equipment manufacturer.
- 9. Our liability is only assumed for the Surface Acoustic Wave (SAW) component(s) per se, not for applications, processes and circuits implemented within components or assemblies.
- 10. For questions on technology, prices and delivery, please contact our sales offices or e-mail sales@hoperf.com.